

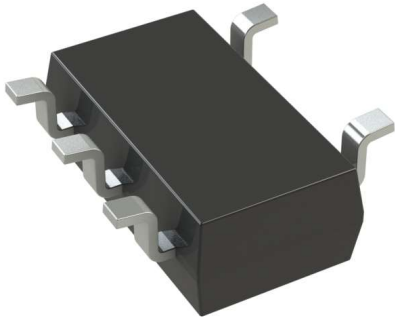
Small Outline Packages

SOT

Compact Size: SOT packages are small and lightweight, making them ideal for high-density PCB designs¹.

Surface Mount: They are designed for surface mounting, which simplifies the assembly process and reduces the need for through-hole components¹.

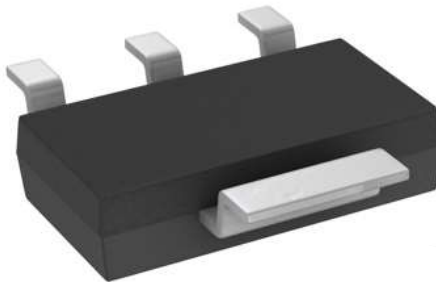
Lead Configuration: SOT packages typically feature gull-wing or J-lead configurations, which provide good mechanical stability and ease of soldering¹.



SOT 23

Suchi Semicon Offers

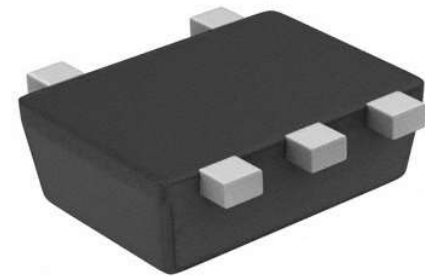
- Lead Count: 3 or 5
- MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- ROHS Compliance



SOT 223

Suchi Semicon Offers

- Lead Count: 4 with pitch of 2.3mm
- MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- ROHS Compliance



SOT 5X3

Suchi Semicon Offers

- MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- ROHS Compliance